

规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_  
PRODUCT 产品: \_\_\_\_\_ SAW FILTER \_\_\_\_\_  
MODEL NO 型号: \_\_\_\_\_ HDF395A2F11 \_\_\_\_\_  
PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_  
APPROVED 批准: \_\_\_\_\_ DATE 日期: \_\_\_\_\_ 2006-5-11 \_\_\_\_\_

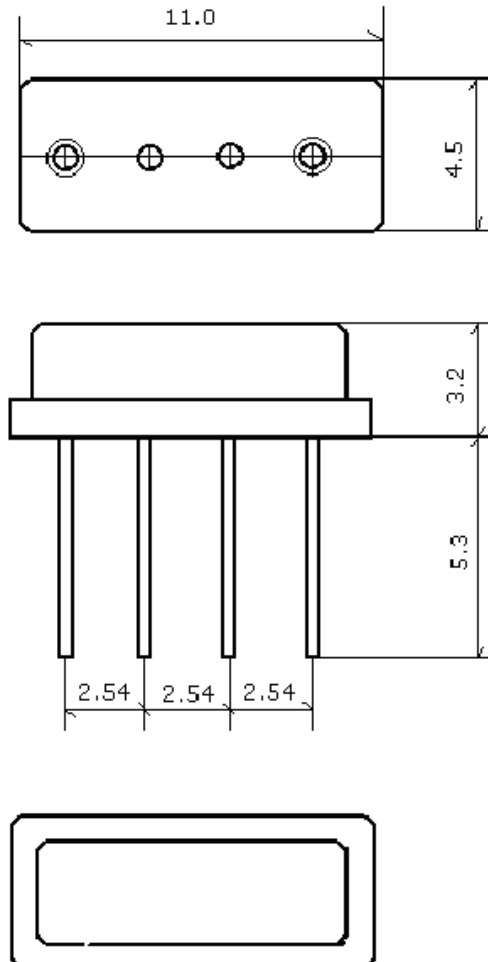
客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited

## 更改历史记录 History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

## 1. Package Dimension



## 2. Marking

### HDF395A

1. Color: Black or Blue
2. 395: Center Frequency (MHz)

## 3. Performance

### 3.1 Application

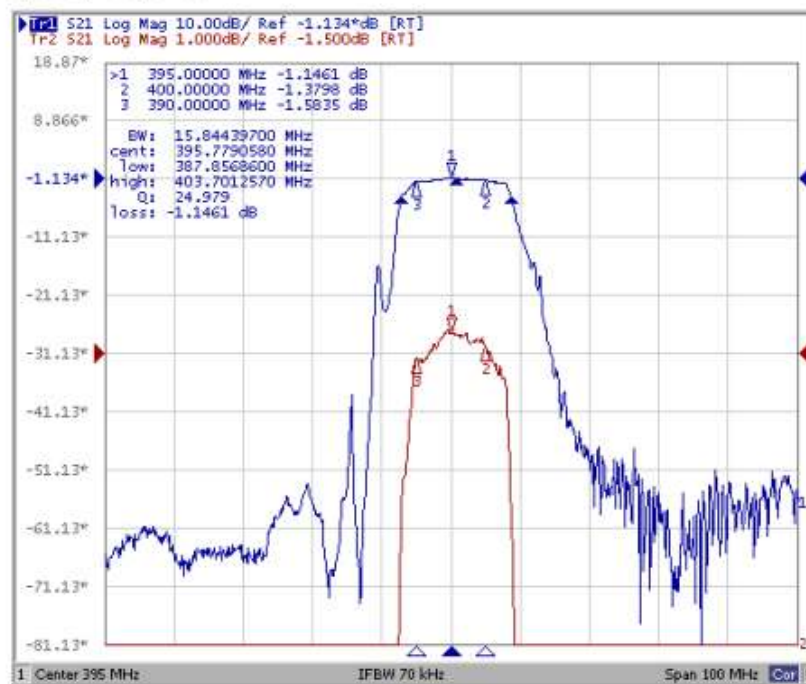
- Low-Loss SAW Filter of cordless system.
- Center Frequency: 395 MHz

**3.2 Maximum Rating**

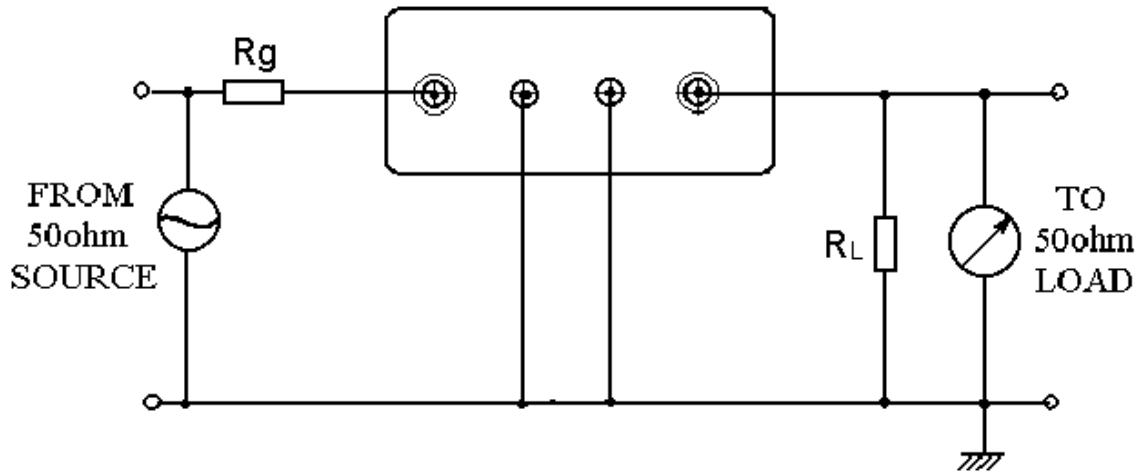
Operation Temperature Range	-40°C to +85°C
Storage Temperature Range	-45°C to +85°C
DC. Permissive Voltage	0 V DC. max.
Maximum Input Power	5dBm

**3.3 Electronic Characteristics**

	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	-	395	-
Insertion Loss (In Fc +/- 5 MHz)	dB		1.5	3.0
Amplitude Ripple (In Fc +/- 5 MHz)	dB		0.5	1.0
VSWR(In Fc +/- 5 MHz)			1.5	2.0
Relative Attenuation 0.3 MHz ~ 365 MHz	dB	40	60	-
425 MHz ~ 1000MHz		40	50	
Input/Output Impedance	Ohms		50	

**3.4 Frequency Characteristics**


### 3.5 Test Circuit



## 4. ENVIRONMENTAL CHARACTERISTICS

### 4-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 3.3.

### 4-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 3.3.

### 4-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 3.3.

### 4-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C ±10°C for 10±1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 3.3.

### 4-5 Solderability

Subject the device terminals into the solder bath at 245°C ±5°C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 3.3.

### 4-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. The device shall fulfill the specifications in 3.3.

### 4-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 3.3.

## **5. REMARK**

### 5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.